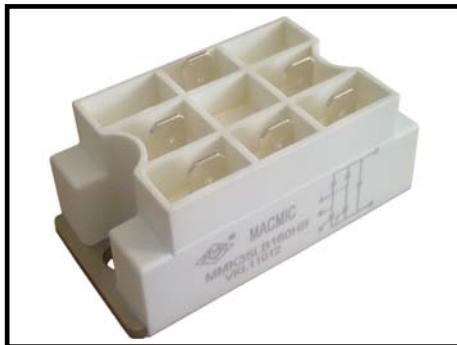
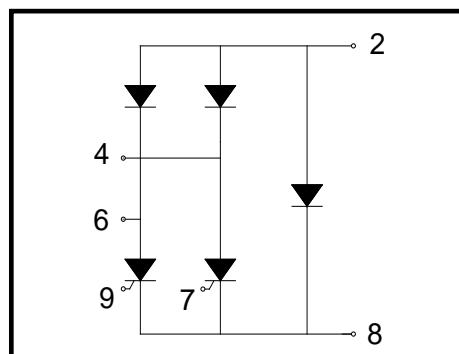


**Features**

- Isolated Module Package
- Isolation voltage 3000 V
- 1/4" fast-on terminals


**Applications**

- Supply for DC power Equipment
- DC Motor Control


**■ Diode**
**ABSOLUTE MAXIMUM RATINGS**
 $T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Max.	Unit
$V_{RRM}$	Repetitive Reverse Voltage		1600	V
$I_{D(AV)}$	Average Forward Current	$T_C=90^\circ\text{C}$ , module	25	A
$I_{FSM}$	Non-Repetitive Surge Forward Current	$T_J=45^\circ\text{C}$ , $t=10\text{ms}$ , 50Hz, Sine	250	A
		$T_J=45^\circ\text{C}$ , $t=8.3\text{ms}$ , 60Hz, Sine	300	A
$I^2t$	$I^2t$ (For Fusing)	$T_J=45^\circ\text{C}$ , $t=10\text{ms}$ , 50Hz, Sine	312	$\text{A}^2\text{s}$
		$T_J=45^\circ\text{C}$ , $t=8.3\text{ms}$ , 60Hz, Sine	450	$\text{A}^2\text{s}$
$T_J$	Junction Temperature		-40~150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-40~125	$^\circ\text{C}$
$V_{isol}$	Insulation Test Voltage	AC, 50Hz, $t=5\text{s}$	3500	V
Weight			93	g

**ELECTRICAL AND THERMAL CHARACTERISTICS**
 $T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$I_{RM}$	Reverse Leakage Current	$V_R=1600\text{V}$	--	--	300	$\mu\text{A}$
		$V_R=1600\text{V}$ , $T_J=125^\circ\text{C}$	--	--	5	mA
$V_F$	Forward Voltage	$I_F=25\text{A}$	--	0.98	--	V
		$I_F=25\text{A}$ , $T_J=125^\circ\text{C}$	--	0.9	--	V
$R_{\theta JC}$	Thermal Resistance Junction-to-Case	per diode	--	--	1.2	$^\circ\text{C}/\text{W}$
		per module	--	--	0.4	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance Case -to-Sink	per diode	--	--	0.6	$^\circ\text{C}/\text{W}$
		per module	--	--	0.2	$^\circ\text{C}/\text{W}$

## ■ Thyristor

### ABSOLUTE MAXIMUM RATINGS

$T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Test Condition	Value	Unit
$V_{RRM}$		1600	V
$I_{T(AV)}$	$T_C=90^\circ\text{C}$ , 180° conduction, half sine wave;	25	A
$I_{TSM}$	$T_J=45^\circ\text{C}$ , $t=10\text{ ms}$ (50Hz), sine, $V_R=V_{RRM}$ ;	300	A
	$T_J=45^\circ\text{C}$ , $t=8.3\text{ ms}$ (60Hz), sine, $V_R=V_{RRM}$ ;	350	
$I^2t$	$T_J=45^\circ\text{C}$ , $t=10\text{ ms}$ (50Hz), sine, $V_R=V_{RRM}$ ;	450	$\text{A}^2\text{s}$
	$T_J=45^\circ\text{C}$ , $t=8.3\text{ ms}$ (60Hz), sine, $V_R=V_{RRM}$ ;	612	
$dv/dt$	$T_J=125^\circ\text{C}$ , Linear to $0.67V_{DRM}$	1000	V/us
$di/dt$	$T_J=125^\circ\text{C}$ , $I_{TM}=90\text{A}$ , from $0.67V_{DRM}$	150	A/us
$V_{ISOL}$	50Hz, all terminals shorted, $t=5\text{s}$ , $I_{ISOL}\leq 1\text{mA}$ ;	3500	V~
$T_J$	Max. junction operating temperature range	-40~125	°C
$T_{STG}$	Max. storage temperature range	-40~125	°C
	Mounting torque(M6)	3 to 5	N·m
	Terminal connection torque(M6)	3 to 5	N·m
	Terminal connection torque(M4)	1 to 2	N·m

### ELECTRICAL AND THERMAL CHARACTERISTICS

$T_C=25^\circ\text{C}$  unless otherwise specified

Symbol	Test Condition	Min.	Typ.	Max.	Unit
$I_{DRM}/I_{RRM}$	$V_D=V_R=1600\text{V}$ ;			0.3	mA
$I_{DRM}/I_{RRM}$	$T_J=125^\circ\text{C}$ , $V_D=V_R=1600\text{V}$ ;			5	mA
$V_{TM}$	$I_{TM}=80\text{A}$ , $t_d=10\text{ ms}$ , half sine;		1.64		V
$V_{GT}$	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_j=-40^\circ\text{C}$ ;			4	V
	$V_A=6\text{V}$ , $R_A=1\Omega$ ;			2.5	
	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_j=125^\circ\text{C}$ ;			1.7	
$I_{GT}$	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_j=-40^\circ\text{C}$ ;			270	mA
	$V_A=6\text{V}$ , $R_A=1\Omega$ ;			150	
	$V_A=6\text{V}$ , $R_A=1\Omega$ , $T_j=125^\circ\text{C}$ ;			80	
$P_{GM}$	$tp\leq 5\text{ms}$ , $T_j=125^\circ\text{C}$ ;			10	W
$P_{GM(AV)}$	$f=50\text{Hz}$ , $T_j=125^\circ\text{C}$ ;			2.5	W
$R_{thjc}$	Thermal Resistance , Junction-to-Case			0.5	K/W
$R_{THCS}$	Thermal Resistance, Case -to-Sink			0.15	K/W

## Characteristic curves

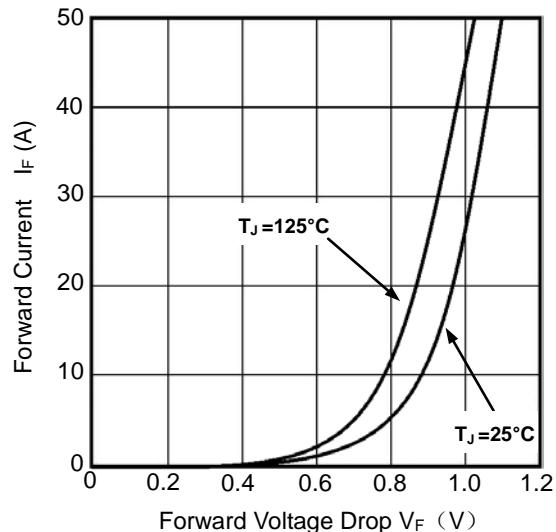


Figure 1. Diode Forward Voltage Drop vs Forward Current

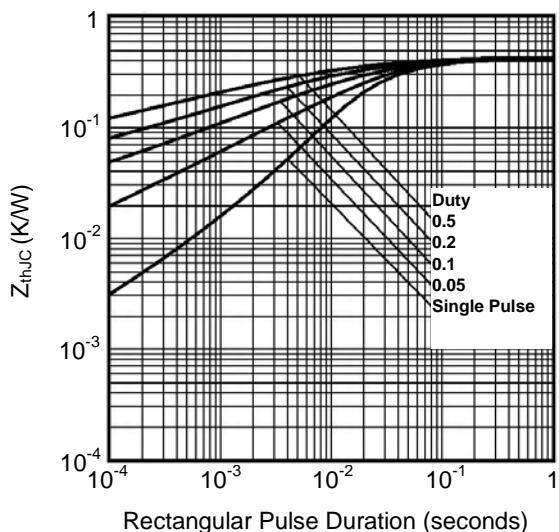
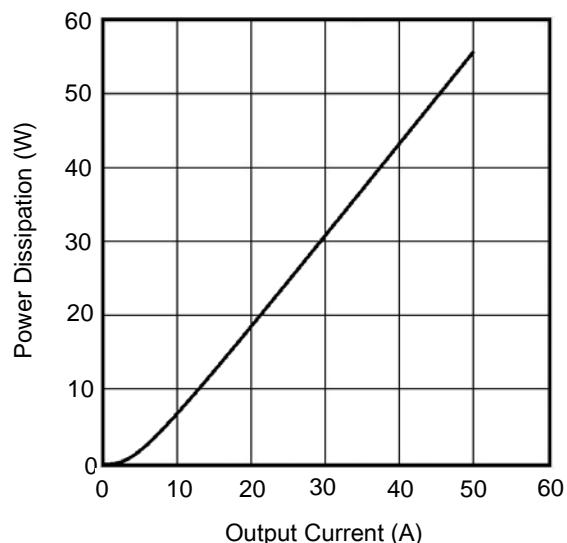
Figure 2. Diode Thermal Impedance Z<sub>thJC</sub>

Figure 3. SCR Output Current vs Power Dissipation

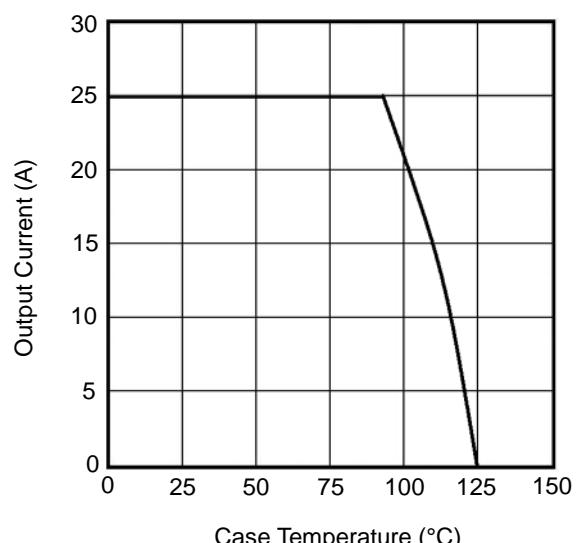


Figure 4. SCR Output Current vs Case Temperature

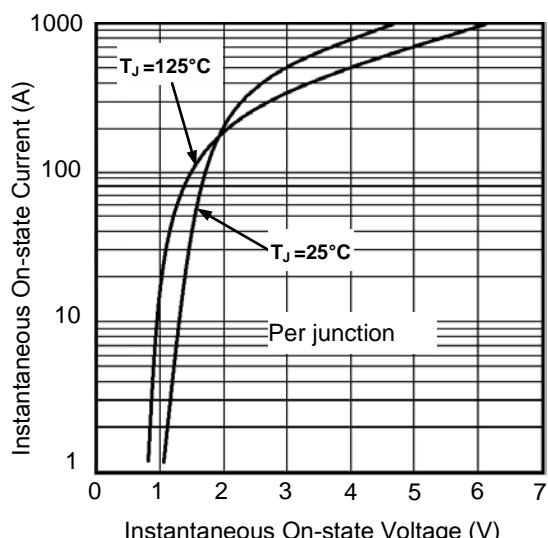
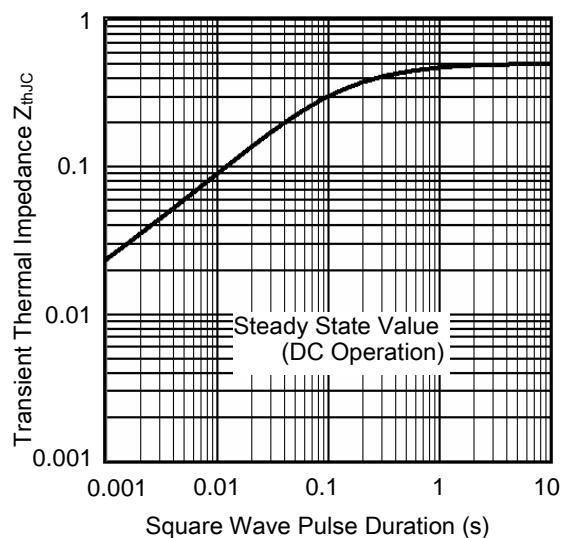


Figure 5. SCR On State Voltage Drop

Figure 6. SCR Thermal Impedance Z<sub>thJC</sub>

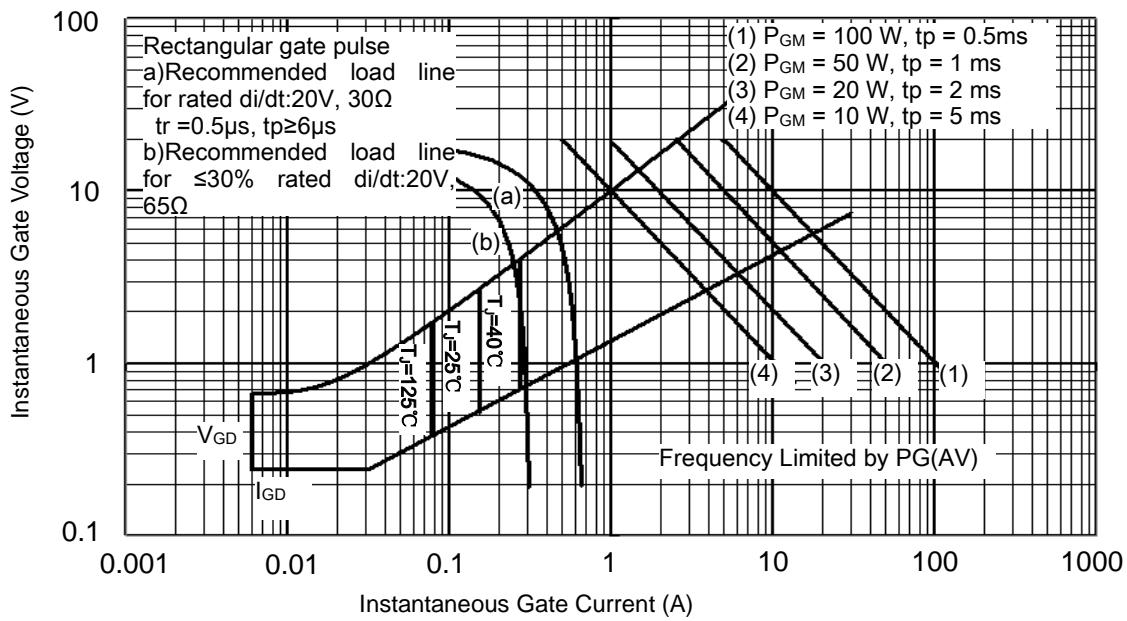


Figure 7. Gate Characteristics

**Package Outline (Dimensions in mm)**